

## General Description

- Advanced Trench MOS Technology
- 100% EAS Guaranteed
- Fast Switching Speed
- Green Device Available

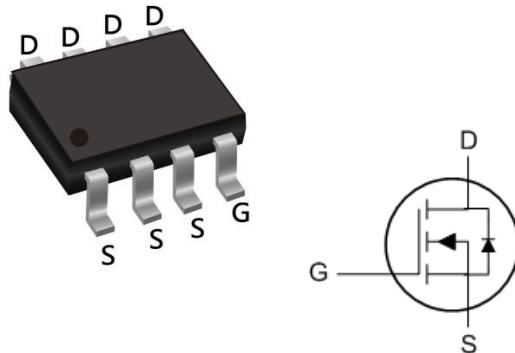
## Product Summary

BVDSS	RDS(ON)	ID
100V	20mΩ	9.3A

## SOP-8 Pin Configuration

## Applications

- Portable Equipment.
- Battery Powered Systems.
- Hard Switching and High-Speed Circuit.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	9.3	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	7.4	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	37	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	45	mJ
I <sub>AS</sub>	Avalanche Current	30	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	3.1	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup> (t≤10S)	---	40	°C/W
	Thermal Resistance Junction-ambient <sup>1</sup> (Steady State)	---	85	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-case <sup>1</sup>	---	24	°C/W

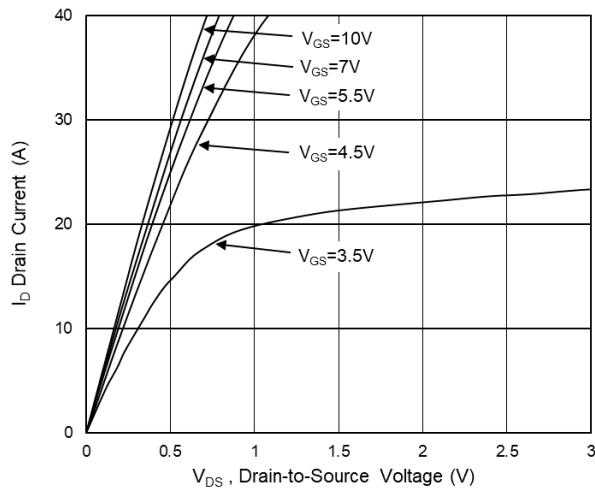
**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	100	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=8\text{A}$	---	16	20	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=6\text{A}$	---	22	30	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	1.2	1.8	2.2	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1.1	---	$\Omega$
$Q_g$	Total Gate Charge	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=8\text{A}$	---	17.9	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	2.8	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	5.2	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=6\Omega$ , $I_D=1\text{A}$	---	13	---	$\text{ns}$
$T_r$	Rise Time		---	6	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	30	---	
$T_f$	Fall Time		---	29	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	849	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	185	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	8	---	
<b>Diode Characteristics</b>						
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	9.3	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.2	V

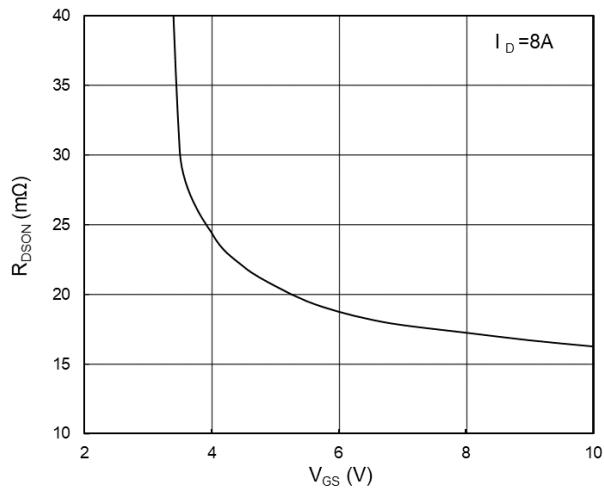
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $L=0.1\text{mH}$ , $I_{\text{AS}}=30\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_s$  , in real applications , should be limited by total power dissipation.

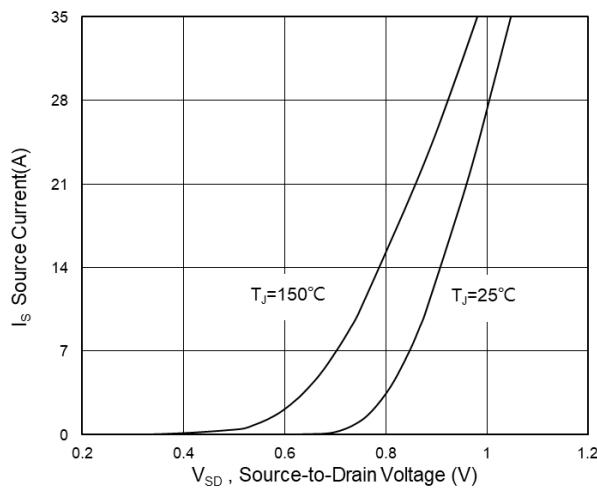
## Typical Characteristics



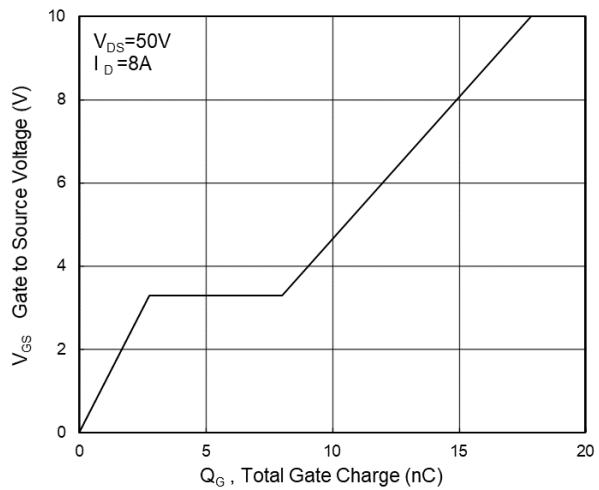
**Fig.1 Typical Output Characteristics**



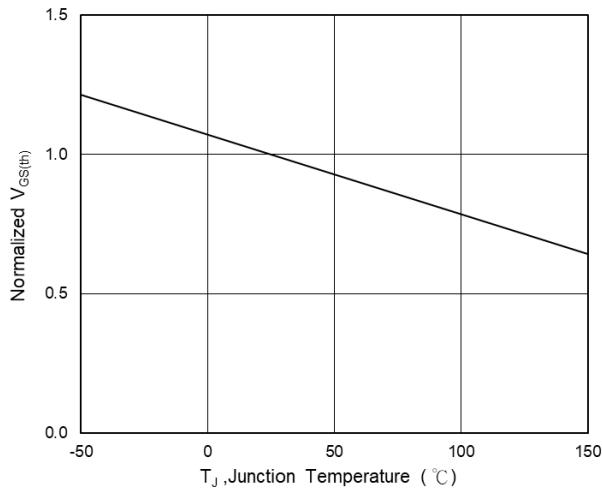
**Fig.2 On-Resistance vs G-S Voltage**



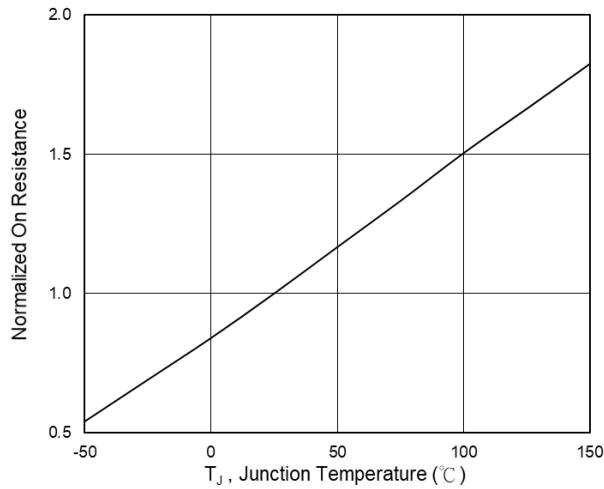
**Fig.3 Source Drain Forward Characteristics**



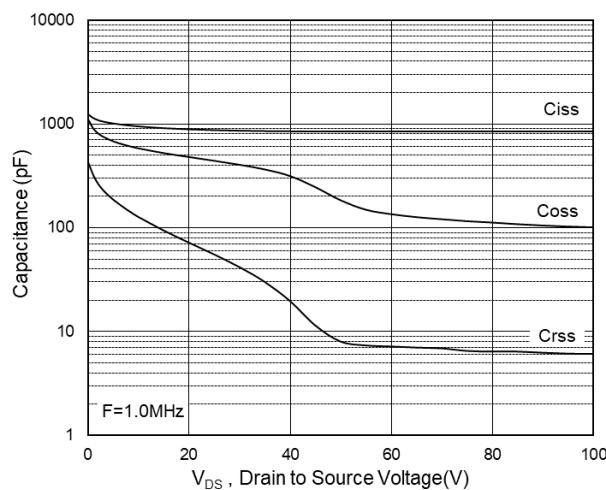
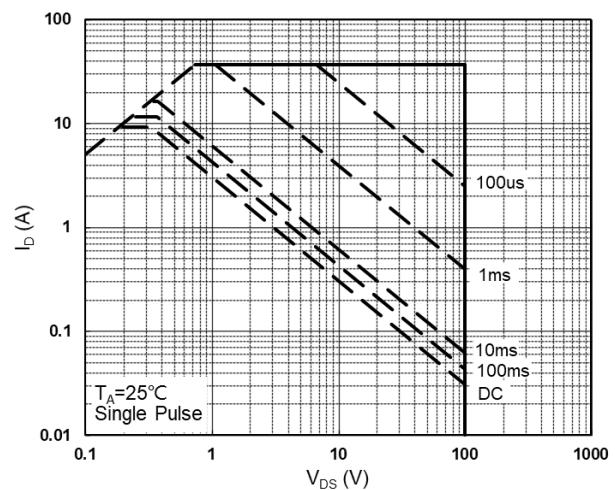
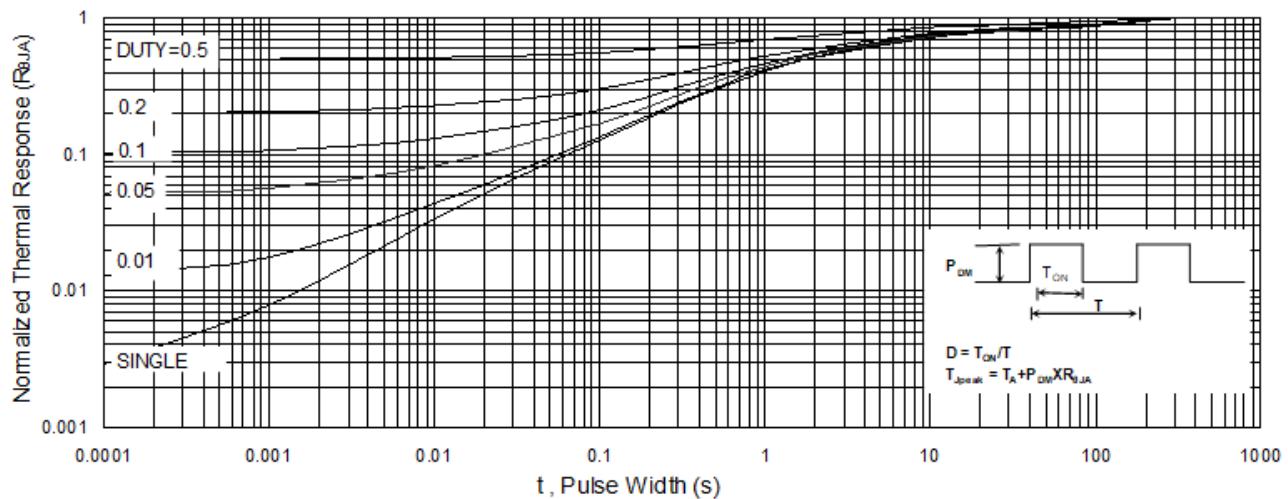
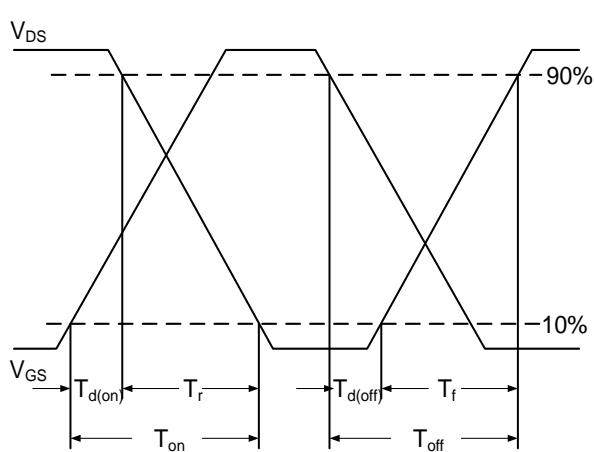
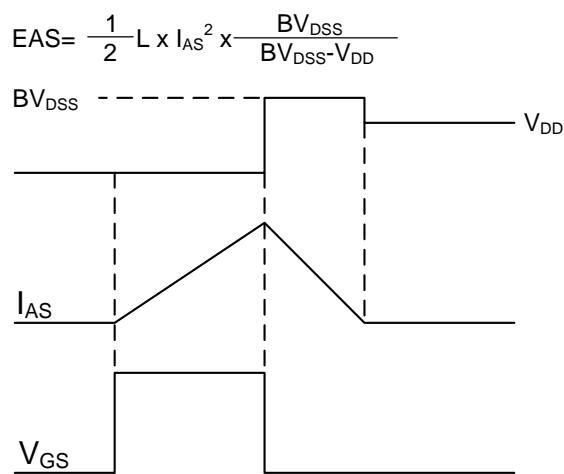
**Fig.4 Gate-Charge Characteristics**



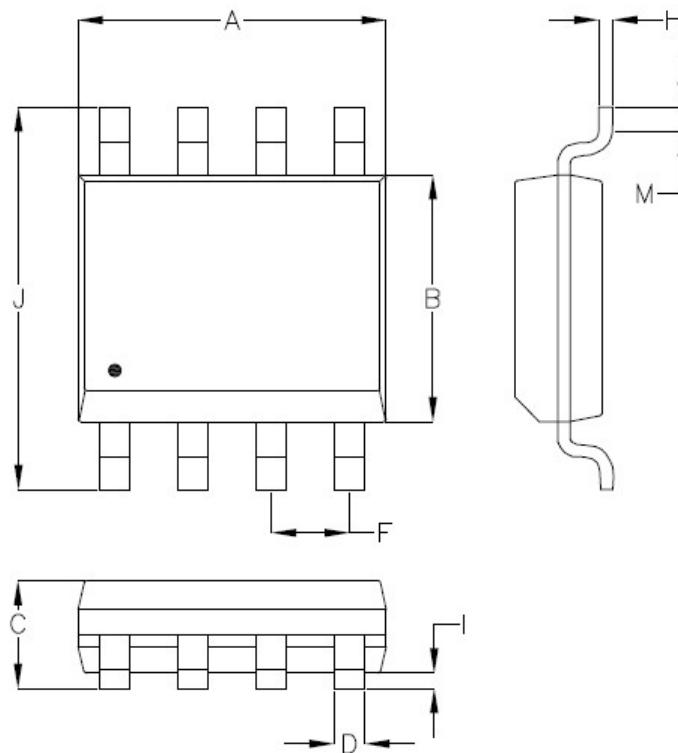
**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**


**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Switching Waveform**

## SOP-8L Package Outline



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.700	5.150	0.185	0.203
B	3.700	4.100	0.146	0.161
C	1.23	1.753	0.048	0.069
D	0.310	0.510	0.012	0.020
F	1.070	1.470	0.042	0.058
H	0.160	0.254	0.006	0.010
I	0.050	0.254	0.002	0.010
J	5.750	6.250	0.226	0.246
M	0.400	1.270	0.016	0.050

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